

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. – 4. (Cancelled)

5. (Currently Amended) A device for forming a wiring, comprising:
a liquid drop ejecting device for ejecting liquid drops onto a substrate by scanning on the substrate in at least first and second scanning movements; and
a surface-treatment device for surface-treating the substrate,
wherein the device for forming a wiring ejects the liquid drops on the substrate such that a predetermined regular interval is disposed between each pair of ejected liquid drops in the first scanning movement, the predetermined interval being twice a diameter of the previously-ejected liquid drop or less,
the liquid drops ejected in the second scanning movement are disposed to fill the predetermined regular intervals, and
the substrate is surface-treated by the ~~surface-treatment~~ surface-treatment device so that a contact angle of the ejected liquid drops with respect to the substrate is in a predetermined range, and
a volume of the liquid drops ejected in the first scanning movement is equal to a volume of the liquid drops ejected in the second scanning movement.

6. (Previously Presented) A device for forming wiring according a wiring according to Claim 5, wherein the contact angle is in a range of 15° to 45°.

7. – 15. (Cancelled)

16. (Previously Presented) A device for forming wiring according to Claim 5, wherein the predetermined regular intervals are determined by controlling: a relative speed of the liquid drop ejecting device with respect to the substrate; and a frequency of the ejection by the liquid drop ejecting device.